

SHEET 2 OF 2

INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION

(PTO-1449)



ATTY. DOCKET NO.  
004066  
USA/Consilium/Consilium

SERIAL NO.  
09/363,966

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Technology Center 2100

APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
July 29, 1999

GROUP  
2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,889,991	03/30/99	Consolatti et al.			12/06/96
	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
	6,298,470 B1	10/02/01	Breiner et al.			04/15/99

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
	Jensen, Alan, Peter Renteln, Stephen Jew, Chris Raeder, and Patrick Cheung. June 2001. "Empirical-Based Modeling for Control of CMP Removal Uniformity." Solid State Technology, Vol. 44, No. 6, pp. 101-102, 104, 106. Cowan Publ. Corp.: Washington, D.C.
	Sarfaty, Moshe, Arulkumar Shanmugasundram, Alexander Schwarm, Joseph Paik, Jimin Zhang, Rong Pan, Martin J. Seamons, Howard Li, Raymond Hung, and Suketu Parikh. April/May 2002. "Advance Process Control Solutions for Semiconductor Manufacturing." IEEE/SEMI Advanced Semiconductor Manufacturing Conference. pp. 101-106.
	October 4, 2002. International Search Report from PCT/US01/22833.
	October 23, 2002. International Search Report from PCT/US01/27406.
	November 7, 2002. International Search Report from PCT/US02/19061.
	November 11, 2002. International Search Report from PCT/US02/19117.
	November 12, 2002. International Search Report from PCT/US02/19063.

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5/28/03

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**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,270,222	12/14/93	Moslehi			12/31/90
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	5,599,423	02/04/97	Parker et al.			06/30/95
	5,844,554	12/01/98	Geller et al.			09/17/96

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						Yes	No
	WO 95/34866	12/21/95	WO			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	WO 99/25520	05/27/99	WO			X	
	WO 00/54325	09/14/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
	EP 1 092 505 A2	04/18/01	Europe			X	

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	Hu, Albert, Kevin Nguyen, Steve Wong, Xiuhua Zhang, Emanuel Sachs, and Peter Renteln. 1993. "Concurrent Deployment of Run by Run Controller Using SCC Framework." IEEE/SEMI International Semiconductor Manufacturing Science Symposium. pp. 126-132.
	Hu, Albert, He Du, Steve Wong, Peter Renteln, and Emanuel Sachs. 1994. "Application of Run by Run Controller to the Chemical-Mechanical Planarization Process." IEEE/CPMT International Electronics Manufacturing Technology Symposium. pp. 371-378.
	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996: "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Proceedings of the Thirteenth International VLSI Multilevel Interconnection Conference. pp. 437-439.
	Suzuki, Junichi and Yoshikazu Yamamoto. 1998. "Toward the Interoperable Software Design Models: Quartet of UML, XML, DOM and CORBA." Proceedings IEEE International Software Engineering Standards Symposium. pp. 1-10.
	Klein, Bruce. June 1999. "Application Development: XML Makes Object Models More Useful." Informationweek. pp. 1A-6A.

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John F. ARACKAPARAMBIL et al.

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
SNB	3,767,900	10/23/73	Chao et al.			06/23/71
SNB	3,920,965	11/18/75	Sohrwardy			03/04/74
SNB	4,368,510	01/11/83	Anderson			10/20/80
SNB	4,616,308	10/07/86	Morshedi et al.			12/02/85
SNB	4,663,703	05/05/87	Axelby et al.			10/02/85
SNB	5,347,446	09/13/94	Iino et al.			02/10/92
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SNB	2001/0040997	11/15/01	Tsap et al.			05/15/01
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FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SNB	EP 1 067 757	01/10/01	Europe			X	
SNB	WO 01/33277	05/10/01	WO			X	
SNB	WO 02/31613 A2	04/18/02	WO			X	
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SNB	23 May 2003. Written Opinion for PCT/US01/24910.

EXAMINER	DATE CONSIDERED
SNB	9/16/07

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				APPLICANT John F. ARACKAPARAMBIL et al.	<b>RECEIVED</b> OCT 20 2003 Technology Center 2100	
				FILING DATE July 29, 1999	GROUP 2125	
<b>U.S. PATENT DOCUMENTS</b>						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
Snw	5,901,313	05/04/99	Wolf et al.			09/02/97
Snw	6,002,989	12/14/99	Shiba et al.			04/01/97
Snw	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
Snw	6,340,602	01/22/02	Johnson et al.			02/12/01
Snw	6,345,288	02/05/02	Reed et al.			05/15/00
Snw	6,368,879	04/09/02	Toprac			09/22/99
Snw	US-2002/0107604	08/08/02	Riley et al.			12/06/00
Snw	6,470,230	10/22/02	Toprac et al.			01/04/00
Snw	6,482,660	11/19/02	Conchieri et al.			03/19/01
Snw	6,567,717	05/20/03	Krivokapic et al.			01/19/00
<b>FOREIGN PATENT DOCUMENTS</b>						
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation
						Yes
Snw	WO 99/59200	11/18/99	WIPO			X
Snw	WO 01/52319	07/19/01	WIPO			X
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>						
Snw	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.					
Snw	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.					
Snw	01 August 2003. Written Opinion for PCT/US01/27406.					
Snw	20 August 2003. Written Opinion for PCT/US01/22833.					
EXAMINER				DATE CONSIDERED		
<i>Snw</i>				<i>7/16/04</i>		

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SHEET 1 OF 2 #34

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APPLICANT  
John F. ARACKAPARAMBIL et al.

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
Sn 6	4,207,520	06/10/80	Flora et al.			04/06/78
Sn 0	4,209,744	06/24/80	Gerasimov et al.			03/27/78
Sn 0	4,609,870	09/02/86	Lale et al.			09/13/84
Sn b	4,755,753	07/05/88	Chern			07/23/86
Sn 0	5,427,878	06/27/95	Corliss			05/16/94
Sn 0	5,534,289	07/09/96	Bilder et al.			01/03/95
Sn b	5,867,389	02/02/99	Hamada et al.			11/26/96
Sn 0	6,041,263	03/21/00	Boston et al.			10/01/97
Sn 0	6,077,412	06/20/00	Ting et al.			10/30/98
Sn 0	6,271,670	08/07/01	Caffey			02/08/99
Sn 0	6,400,162	06/04/02	Mallory et al.			07/21/00
Sn 0	US 2002/0077031	06/20/02	Johansson et al.			07/06/01
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Sn 0	6,563,308	05/13/03	Nagano et al.			03/27/01
Sn 0	6,587,744	07/01/03	Stoddard et al.			06/20/00

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
Sn b	WO 01/11679	02/15/01	WIPO			X	
Sn 0	WO 01/080306	10/25/01	WIPO			X	

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Sn 0	Miller, G. L., D. A. H. Robinson, and J. D. Wiley. July 1976. "Contactless measurement of semiconductor conductivity by radio frequency-free-carrier power absorption." <i>Rev. Sci. Instrum.</i> , Volume 47, No. 7. pp. 799 – 805.
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Sn 0	2000. "Microsense II Capacitance Gaging System." <a href="http://www.adetech.com">www.adetech.com</a> . 2000.

EXAMINER

DATE CONSIDERED

*Marcel*

*9/16/04*

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O.P.E. SCITA  
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## INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

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09/368,966

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APPLICANT  
John F. ARACKAPARAMBIL et al.

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### FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No

### OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

SNL	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." <i>J. Vac. Sci. Technol.</i> Volume 18, No. 4. pp. 1287 - 1296, July/August 2000.
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SNL	2002. "Microsense II - 5810: Non-Contact Capacitance Gaging Module." <a href="http://www.adetech.com">www.adetech.com</a> .
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SNL	23 October 2003. PCT International Preliminary Examination Report from PCT/US01/24910.
SNL	"NanoMapper wafer nanotopography measurement by ADE Phase Shift." <a href="http://www.phase-shift.com/nanomap.shtml">http://www.phase-shift.com/nanomap.shtml</a> . 12/9/03
SNL	"Wafer flatness measurement of advanced wafers." <a href="http://www.phase-shift.com/wafer-flatness.shtml">http://www.phase-shift.com/wafer-flatness.shtml</a> . 12/9/03
SNL	"ADE Technologies, Inc." <a href="http://www.adetech.com/6360.shtml">http://www.adetech.com/6360.shtml</a> . 12/9/03
SNL	"3D optical profilometer MicroXAM by ADE Phase Shift." <a href="http://www.phase-shift.com/microxam.shtml">http://www.phase-shift.com/microxam.shtml</a> . 12/9/03
SNL	"NanoMapper FA factory automation wafer nanotopography-measurement." <a href="http://www.phase-shift.com/nanomapperfa.shtml">http://www.phase-shift.com/nanomapperfa.shtml</a> . 12/9/03

EXAMINER	DATE CONSIDERED
Gardel	9/10/04

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SHEET 1 OF 5

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>		ATTY. DOCKET NO. 004066 USA/Consilium/Consilium	SERIAL NO. 09/363,966
<b>APPLICANT</b> John F. ARACKAPARAMBIL et al.			
FILING DATE July 29, 1999	GROUP 2125		

**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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	5,240,552	08/31/93	Yu et al.			12/11/91
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	5,444,837	08/22/95	Bomans et al.	Technology Center 2100		12/29/93
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	6,150,270	11/21/00	Matsuda et al.			01/07/99
	6,150,664	11/21/00	Su			06/29/99

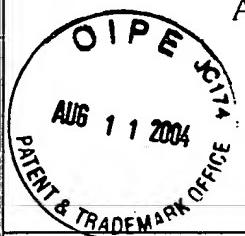
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			FILING DATE July 29, 1999	GROUP 2125		
U.S. PATENT DOCUMENTS						
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	6,157,864	12/05/00	Schwenke et al.			05/08/98
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EXAMINER <i>Goyal</i>			DATE CONSIDERED <i>9/16/04</i>			

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**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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AUG 13 2004  
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						Yes	No
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	EP 1 083 470 A2	03/14/01	EP			X	
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EXAMINER

*Markland*

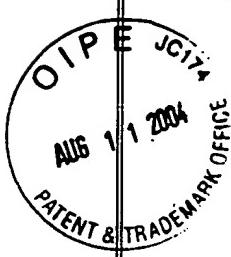
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*9/16/04*

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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>		ATTY. DOCKET NO. 004066 USA/Consilium/Consilium	SERIAL NO. 09/363,966 <b>RECEIVED</b>
		APPLICANT John F. ARACKAPARAMBIL	<b>Technology Center 2100</b>
		FILING DATE July 29, 1999	GROUP 2125
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**INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)**

ATTY. DOCKET NO.  
004066  
USA/Consilium/Consilium

SERIAL NO.  
09/363,966

APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
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